

6367254 MOTOROLA SC (XSTRS/R F)

96D 80785 D

T-33-29

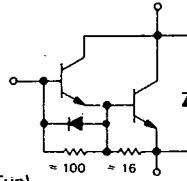
MOTOROLA
SEMICONDUCTOR
TECHNICAL DATA

BUT16

SWITCHMODE SERIES
NPN SILICON POWER DARLINGTON TRANSISTORS
WITH BASE-EMITTER SPEEDUP DIODE

The BUT16 Darlington transistor is designed for high-voltage, high-speed, power switching in inductive circuits where fall time is critical. They are particularly suited for line-operated switchmode applications such as:

- AC and DC Motor Controls
- Switching Regulators
- Inverters
- Solenoid and Relay Drivers
- Fast Turn-Off Times
2.0 uS Inductive Fall Time at 100°C (Typ)
0.8 uS Inductive Storage Time at 100°C (Typ)
- Operating Temperature Range -65 to 175°C

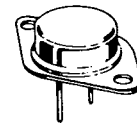


12 AMPERES
NPN SILICON
POWER DARLINGTON
TRANSISTORS

1400 VOLTS
150 WATTS

Designer's Data for
"Worst Case" Conditions

The Designers Data Sheet permits the design of most circuits entirely from the information presented. Limit data - representing device characteristics boundaries - are given to facilitate "worst case" design.



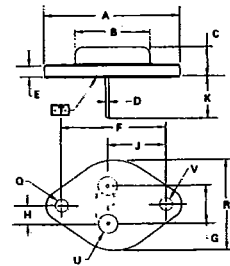
MAXIMUM RATINGS

Rating	Symbol	BUT16	Unit
Collector-Emitter Voltage	$V_{CE(sus)}$	1000	Vdc
Collector-Emitter Voltage	V_{CEV}	1400	Vdc
Emitter Base Voltage	V_{EB}	10	Vdc
Collector Current			Adc
- Continuous	I_C	12	
- Peak (1)	I_{CM}	20	
Base Current			Adc
- Continuous	I_B	8	
- Peak (1)	I_{BM}	10	
Free Wheel Diode:			Adc
Forward current - Continuous	I_F	12	
- Peak	I_{FM}	20	
Total Power Dissipation @ $T_C = 25^\circ C$	P_D	150	Watts
Derate above 25°C @ $T_C = 100^\circ C$		75	W/°C
Operating and Storage Junction Temperature Range	T_J, T_{stg}	-65 to +175	°C

THERMAL CHARACTERISTICS

Characteristic	Symbol	Max	Unit
Thermal Resistance, Junction to Case	$R_{\theta JC}$	1.0	°C/W
Maximum Lead Temperature for Soldering Purpose: 1/8" from Case for 5 Seconds	T_L	275	°C

(1) Pulse Test. Pulse Width = 5 ms, Duty Cycle \leq 10%.



- NOTES
1 DIMENSIONS O AND V ARE DATUMS
2 \square IS SEATING PLANE AND DATUM
3 POSITIONAL TOLERANCE FOR MOUNTING HOLE \odot

ϕ .13 (10 005) \odot T ∇ \odot

FOR LEADS

ϕ .13 (10 005) \odot T ∇ \odot \odot

4 DIMENSIONS AND TOLERANCES PER ANSI Y14.5, 1973

DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	39.27	-	1.550	-
B	21.08	-	0.830	-
C	6.35	7.62	0.250	0.300
D	0.97	1.09	0.038	0.043
E	-	3.43	-	0.135
F	30.15 BSC	-	1.187 BSC	-
G	10.92 BSC	-	0.430 BSC	-
H	5.46 BSC	-	0.215 BSC	-
J	16.89 BSC	-	0.665 BSC	-
K	11.18	12.19	0.440	0.480
O	3.81	4.19	0.150	0.165
R	-	26.67	-	1.050
U	4.83	5.33	0.190	0.210
V	3.81	4.19	0.150	0.165

CASE 1-05 TO-3

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ELECTRICAL CHARACTERISTICS (TC = 25°C unless otherwise noted)

Characteristic	Symbol	Min	Typ	Max	Unit
OFF CHARACTERISTICS					
Collector-Emitter Sustaining Voltage (Table 1) (IC = 100 mA, IB = 0)	VCE(sus)	1000	-	-	Vdc
Collector Cutoff Current (VCEV = Rated Value, VBE(off) = 1.5 Vdc) (VCEV = Rated Value, VBE(off) = 1.5 Vdc, TC = 100°C)	ICEV	-	-	0.1 2.0	mAdc
Emitter Cutoff Current (VEB = 2.0 V, IC = 0)	IEBO	-	-	175	mAdc

SECOND BREAKDOWN

Second Breakdown Collector Current with base forward biased	IS/b			See Figure 16	
Clamped Inductive SOA with Base Reverse Biased	RBSOA			See Figure 17	

ON CHARACTERISTICS (1)

DC Current Gain (IC = 4 A, VCE = 5 V) (IC = 8 A, VCE = 5 V)	hFE	20 5	- -	- -	
Collector-Emitter Saturation Voltage (IC = 12 A, IB = 6 A)	VCE(sat)	-	-	5.0	Vdc
Base-Emitter Saturation Voltage (IC = 8 A, IB = 1.6 A)	VBE(sat)	-	-	3.3	Vdc
Diode Forward Voltage (IF = 12 A)	Vf	-	-	4.0	Vdc

SWITCHING CHARACTERISTICS

Inductive Load, Clamped (Table 1)

Storage Time	TC = 25°C	See Table 1 IC = 8 A	ts	-	-	3.3	μs
Fall Time			tf	-	-	1.5	μs
Storage Time	TC = 100°C	IB1 = 1.6 A VBE(off) = 5 V	ts	-	2.0	-	μs
Fall Time			tf	-	0.8	-	μs

(1) Pulse Test: PW = 300 μs, Duty Cycle ≤ 2%.



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TYPICAL CHARACTERISTICS

FIGURE 1 - DC CURRENT GAIN

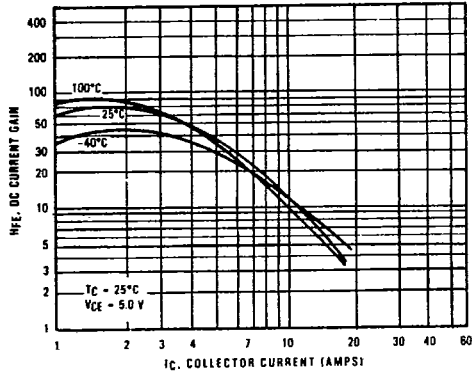


FIGURE 2 - COLLECTOR SATURATION REGION

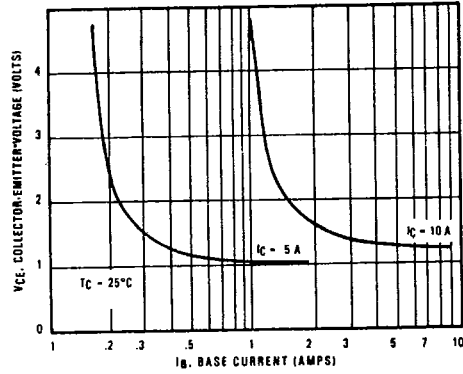


FIGURE 3 - COLLECTOR-EMITTER SATURATION VOLTAGE

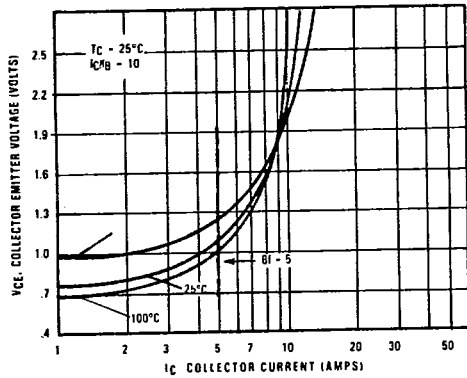


FIGURE 4 - BASE-EMITTER VOLTAGE

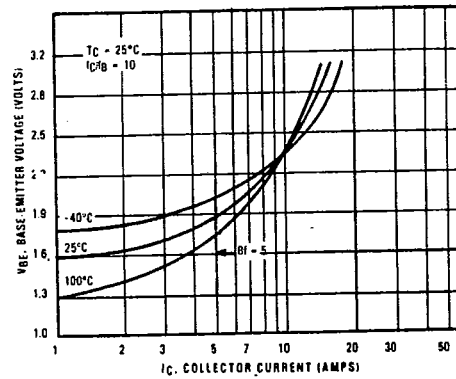
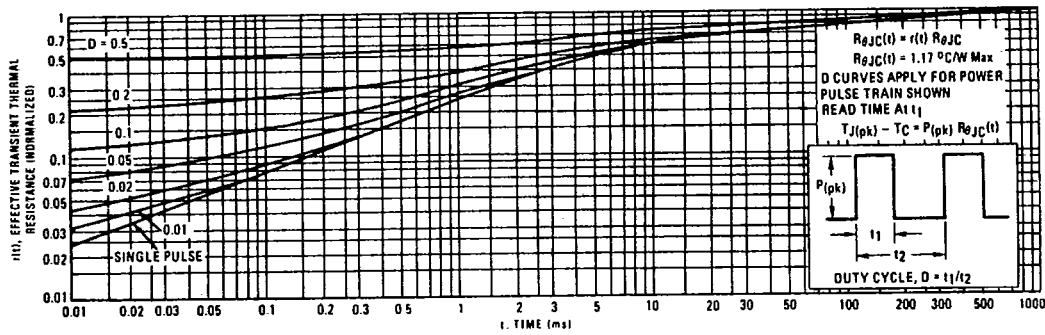


FIGURE 5 - THERMAL RESPONSE



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TABLE 1 - TEST CONDITIONS FOR DYNAMIC PERFORMANCE

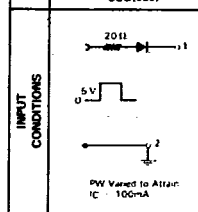
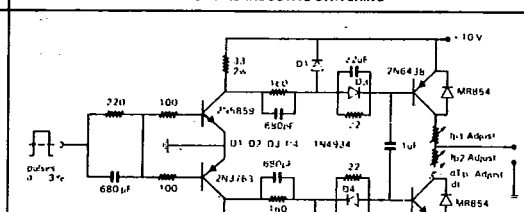
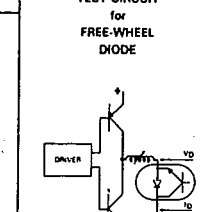
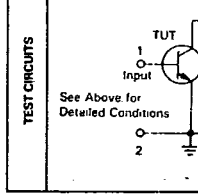
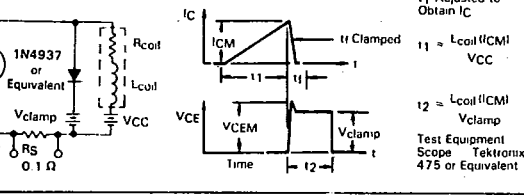
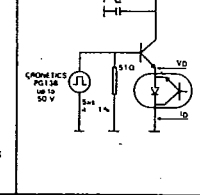
<p>INPUT CONDITIONS</p>  <p>5V 20ns PW Varied to Attain $I_C = 100\text{mA}$</p>	<p>RBSOA AND INDUCTIVE SWITCHING</p> 	<p>TEST CIRCUIT for FREE-WHEEL DIODE</p> 
<p>CIRCUIT VALUES</p> <p>$L_{coil} = 10\text{ mH}$ $V_{CC} = 10\text{V}$ $R_{coil} = 0.7\ \Omega$ $V_{clamp} = V_{CE0}(sus)$</p>	<p>$L_{coil} = 180\ \mu\text{H}$ $R_{coil} = 0.05\ \Omega$ $V_{CC} = 10\text{V}$</p>	
<p>INDUCTIVE TEST CIRCUIT</p>  <p>See Above for Detailed Conditions</p>	<p>OUTPUT WAVEFORMS</p>  <p>t_1 Adjusted to Obtain I_C $t_1 = L_{coil} (I_{CM}) / V_{CC}$ $t_2 = L_{coil} (I_{CM}) / V_{clamp}$</p> <p>Test Equipment Scope Tektronix 475 or Equivalent</p>	<p>TEST CIRCUIT for FREE-WHEEL DIODE</p> 

FIGURE 6 - FALL TIME vs I_{B2}/I_{B1}

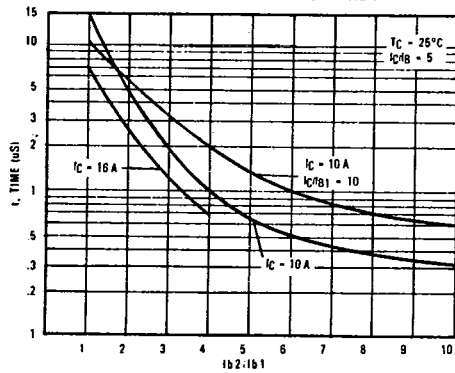


FIGURE 7 - TURN-OFF TIME vs I_C

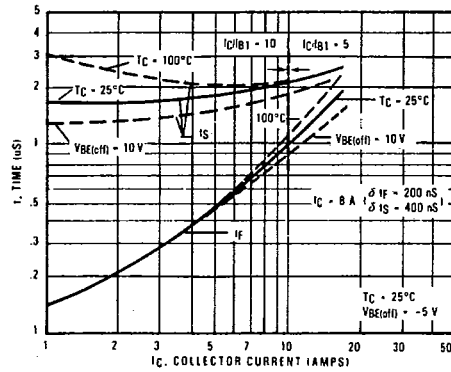


FIGURE 8 - STORAGE TIME vs FORCED GAIN

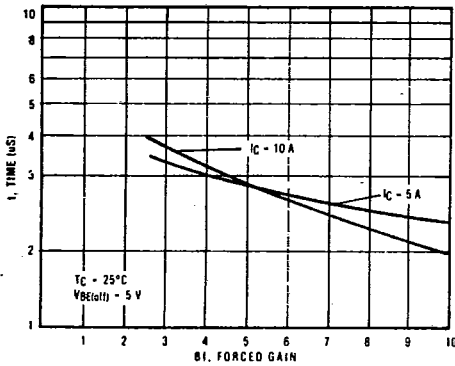
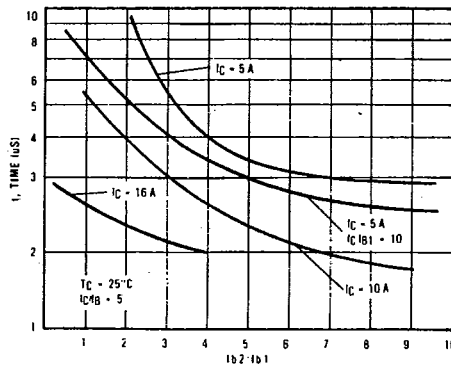


FIGURE 9 - STORAGE TIME vs I_{B2}/I_{B1}



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FREE-WHEEL DIODE CHARACTERISTICS

FIGURE 10 - FREE WHEEL DIODE MEASUREMENTS

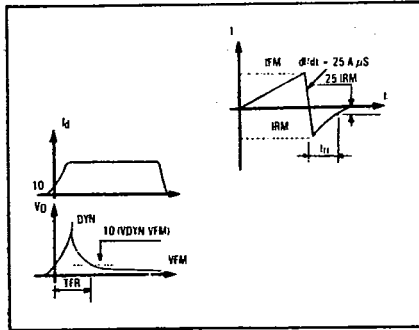


FIGURE 11 - FORWARD VOLTAGE

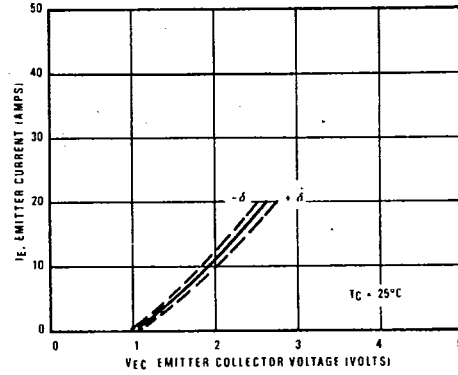


FIGURE 12 - FORWARD MODULATION VOLTAGE

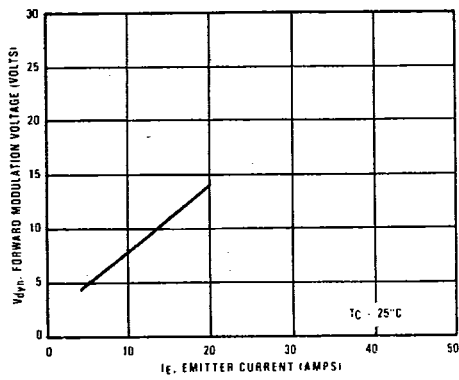


FIGURE 13 - PEAK REVERSE RECOVERY CURRENT

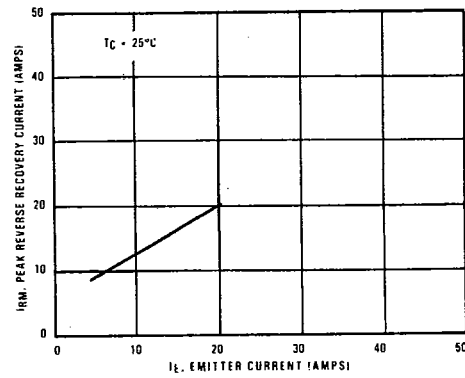


FIGURE 14 - FORWARD RECOVERY TIME

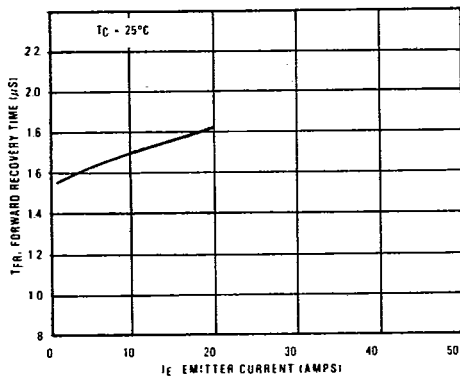
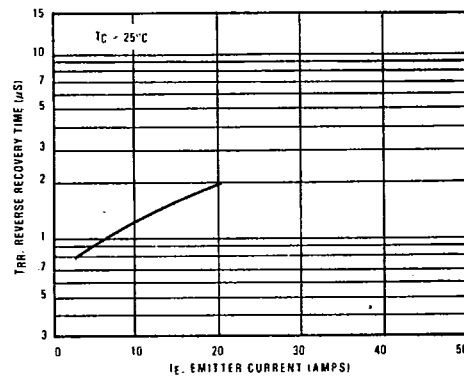


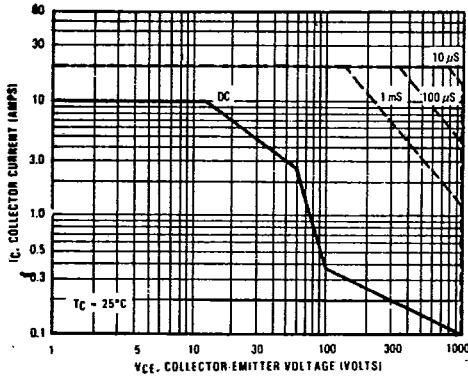
FIGURE 15 - REVERSE RECOVERY TIME



The Safe Operating Area figures shown in Figures 16 and 17 are specified for these devices under the test conditions shown.

SAFE OPERATING AREA INFORMATION

FIGURE 16 — SAFE OPERATING AREA



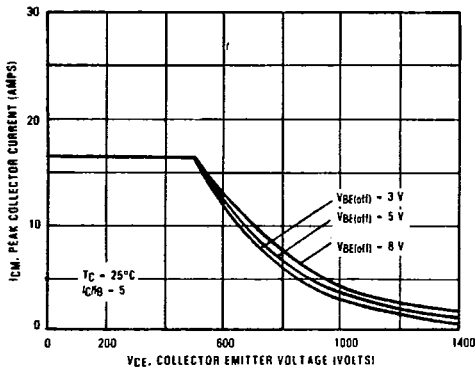
FORWARD BIAS

There are two limitations on the power handling ability of a transistor: average junction temperature and second breakdown. Safe operating area curves indicate IC-VCE limits of the transistor that must be observed for reliable operation, i.e., the transistor must not be subject to greater dissipation than the curves indicate.

The data of Figure 16 is based on Tc = 25°C; TJ(pk) is variable depending on power level. Second breakdown pulse limits are valid for duty cycles to 10% but must be derated when Tc ≥ 25°C. Second breakdown limitations do not derate the same as thermal limitations. Allowable current at the voltages shown on Figure 16 may be found at any case temperature by using the appropriate curve on Figure 18.

TJ(pk) may be calculated from the data in Figure 5. At high case temperatures, thermal limitations will reduce the power that can be handled to values less than the limitations imposed by second breakdown.

FIGURE 17 — REVERSE BIAS SAFE OPERATING AREA



REVERSE BIAS

For inductive loads, high voltage and high current must be sustained simultaneously during turn-off, in most cases, with the base to emitter junction reverse biased. Under these conditions the collector voltage must be held to a safe level at or below a specific value of collector current. This can be accomplished by several means such as active clamping, RC snubbing, load line shaping, etc. The safe level for these devices is specified as Reverse Bias Safe Operating Area and represents the voltage-current condition allowable during reverse biased turn-off. This rating is verified under clamped conditions so that the device is never subjected to an avalanche mode. Figure 17 gives the RBSOA characteristics.

FIGURE 18 — POWER DERATING

